

ABSTRACT OF THE DISCLOSURE

Apparatus for and Method of Manufacturing Electronic Components

An apparatus for manufacturing electronic components comprises a cleaning roller (14) coming into contact with sealing resin (24) of an assembly (15) of cut packages, a water tank (26) provided under the cleaning roller (14), stored water (27) stored in the water tank (26), a water supply pipe (28) spraying water (29) onto the water tank (26), a draining roller (31) pressed against the cleaning roller (14) impregnated with the stored water (27) and a moving mechanism (32) advancing/retreating the draining roller (31). Dust particles adhering to the assembly (15) are removed by adhering to the cleaning roller (14). The dust particles adhering to the cleaning roller (14) are removed by the stored water (27) impregnated into the cleaning roller (14), and this effect of removing the dust particles from the cleaning roller (14) is increased by waves (W) in the stored water (27) and water (R) reflected on the surface of the stored water (27).

FIGURE 2A